

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1 (CURRENTLY AMENDED): An encapsulation composition comprising one or more base oligomer/polymers; one or more diacrylate monomers selected from the group consisting of tricyclodecane dimethanol diacrylate, ~~dicyclopentenyl acrylate, dicyclopentenyl methacrylate,~~ hydroxypivalaldehyde modified trimethylolpropane diacrylate and mixtures thereof; and one or more thixotropic agents.

2 - 4 (CANCELED)

5 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the diacrylate monomer is tricyclodecane dimethanol diacrylate.

6 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the one or more base oligomer/polymers is an acrylated/methacrylated or vinylene-containing oligomer/polymer.

7 (ORIGINAL): The encapsulation composition of claim 1, wherein the thixotropic agent is treated silica.

8 (CANCELED)

9 (ORIGINAL): The encapsulation composition of claim 1, further comprising one or more filler materials.

10 (ORIGINAL): The encapsulation composition of claim 9, wherein the one or more filler materials are selected from the group comprising spherical hollow glass beads, solid glass beads, talc, spherical silica and mixtures thereof.

11 -12 (CANCELED)

13 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, further comprising a silane coupling agent.

14 (ORIGINAL): The encapsulation composition of claim 1, wherein the one or more base oligomer/polymers comprises in the range of about 1 to about 75 weight percent of the composition.

15 (ORIGINAL): The encapsulation composition of claim 14, wherein the one or more base oligomer/polymers comprises in the range of about 20 to about 50 weight percent of the composition.

16 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the one or more diacrylate monomers comprise in the range of about 1 to about 50 weight percent of the composition.

17 (PREVIOUSLY AMENDED): The encapsulation composition of claim 16, wherein the one or more diacrylate monomers comprise in the range of about 10 to about 30 weight percent of the composition.

18 (ORIGINAL): The encapsulation composition of claim 1, wherein the thixotropic agent comprises in the range of about 0.1 to about 8 weight percent of the composition.

19 (ORIGINAL): The encapsulation composition of claim 18, wherein the thixotropic agent comprises in the range of about 2 to about 5 weight percent of the composition.

20 (CANCELED)

21 (ORIGINAL): The encapsulation composition of claim 9, wherein the one or more filler materials comprise in the range of about 1 to about 85 weight percent of the composition.

22 (ORIGINAL): The encapsulation composition of claim 21, wherein the one or more filler materials comprise in the range of about 50 to about 75 weight percent of the composition.

23 -26 (CANCELED)

27 (ORIGINAL): A method of providing encapsulation on an electronic component comprising the step of applying the composition of claim 1 to an electronic component.